

# REFLOW OVEN MR 260



# MR 260

## Description

The MR 260 air convection reflow soldering systems uses re-circulated hot air to accomplish reflow at much lower temperatures than IR systems. Using constant, even heating, a great variety of board sizes will reach reflow temperature with the same heat profile. All heating parameters and registered profiles can be easily observed on built-in 17" LCD display. By eliminating set-up time your production line can work to its fullest capacity.

## Features

- Forced air convection heat to maximum temperatures up to 280°C.
- Forced air convection provides uniform heating and prevents shadowing.
- Three heating zones, one cooling zone; each independently controlled for accurate temperature profiles.
- Digital PID regulators ensuring high stability of each zone temperature.
- Output to external storage device for print-out program data and temperature profiles.
- 4-channel PCB temperature recording

## Technical Specification

- Power requirements: 230 V AC 1-phase
- Rated power max.: 3800 Watts
- 17" LCD
- Dynamic warming-up control ensuring stable temperatures and virtually no overshoot.
- USB port for external storage.
- Profiling software for temperature data recording.
- Graphic display mode for viewing temperature on a time base.
- 3 heating zones, one cooling zone.
- Stainless steel mesh conveyor belt
- Conveyor speed: 10 - 80 cm/min
- Up to 280° C for lead free soldering.
- Clearance for assemblies up to 25mm
- Soldering width: 260 mm
- Length process chamber: 900 mm
- Heat-up time: approx. 15 min.
- Dimensions: 1650 x 500 x 360 mm (L x W x H)
- Net weight: 95 kg